ASSOCIATION CONNECTION ELECTRONICS INDUSTRIES	Material Compos © Copyright 2005. IPC international and Pan-	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				erials and N	ials and Mfg Information					
upplier Inforn	nation				·										
Company name*			Company unique ID			τ	Unique ID Authority				Respon	Response Date*			
nsemi										2025-0	2025-07-31				
Contact Name			Title - Contact			1	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stew	ards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Repres	entative*	Title - Representative]	Phone - Representative*				Email	Email - Representative*				
Product-Env-Stew	ards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Request	Requester Item Number Mfr Ite		tem Number Mfr Item Name				Effective Date	e Versio	on :	Manufacturing Site		Weight*	UOM	Unit Type	
		FDMC86	MC86340 FET 80V 6.5 mOl		ım PQFN33		2025-07-31 PBB		PBB		70.636	mg	Each		
	Proccess Informati							·							
3			Cerminal Base Alloy J-STD-020 M		SL Rating	Peak Process Body Temp					ature Numl	ber of Reflow Cyc	eles		
Matte Ti	n (Sn) - annealed	C	CU Alloy	1			260		C	30	seco	nds 3			
omments															
	ime at peak temperatur														
or more informati	on regarding material co	omposition j	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
irective 2015/863/EU amending RoHS irective 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	8.097	mg	Supplier	Zinc (Zn)	7440-66-6		0.0097	mg
			Supplier	Iron (Fe)	7439-89-6		0.1903	mg
			Supplier	Copper (Cu)	7440-50-8		7.8946	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0024	mg
Die	0.99	mg	Supplier	Silicon (Si)	7440-21-3		0.99	mg
Lead Frame	20.211	mg	Supplier	Zinc (Zn)	7440-66-6		0.0243	mg
			Supplier	Iron (Fe)	7439-89-6		0.475	mg
			Supplier	Copper (Cu)	7440-50-8		19.7057	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0061	mg
Mold Compound-Black	14.236	mg		Epoxy resin	proprietary data		1.8934	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0285	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		12.3141	mg
Plating	25.1	mg	Supplier	Tin (Sn)	7440-31-5		25.1	mg
Solder Paste	1.989	mg	Supplier	Silver (Ag)	7440-22-4		0.0497	mg
			A	Lead (Pb)	7439-92-1	7a	1.8398	mg
			Supplier	Tin (Sn)	7440-31-5		0.0994	mg
Wire Bond - Cu	0.013	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0128	mg